



Material Content Data Sheet



Sales Product Name		TDA5211		Issued		25. September 2017		
MA#		MA000255018						
Package		PG-TSSOP-28-1		Weight*		107.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.457	2.30	2.30	22966	22966
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134561	
	non noble metal	iron	7439-89-6	19.882	18.58	32.04	185822	320383
wire	noble metal	gold	7440-57-5	0.938	0.88	0.88	8768	8768
encapsulation	organic material	carbon black	1333-86-4	0.196	0.18		1833	
	plastics	epoxy resin	-	8.301	7.76		77585	
	inorganic material	silicondioxide	60676-86-0	56.867	53.15	61.09	531486	610904
leadfinish	non noble metal	tin	7440-31-5	1.559	1.46	1.46	14568	14568
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13231	13231
glue	plastics	acrylic resin	-	0.196	0.18		1836	
	noble metal	silver	7440-22-4	0.786	0.73	0.91	7344	9180
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com